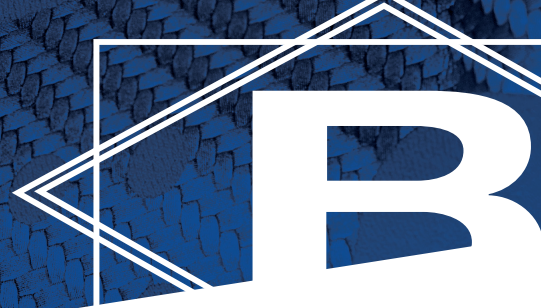


PRODUCT DATA INFORMATION



SEWFREE ADHESIVE (3415)

CONSTRUCTION / SEWFREE ADHESIVE

PRODUCT BENEFITS

Sewfree adhesive is engineered to replace elastics and bulky sewn seams in garments. It allows for sleeker lines, softer corners and stronger seams. 3415 features a low modulus and high recovery and is designed to be used on heat sensitive fabrics where low temperature activation and high elasticity is required.

Intimates: V-fold, lay-down edge treatment, gasket cut wing, fully bonded wing and embellishments

Outerwear / Performance: Overlap seams, pocket attachment, zipper attachment, die cut openings and hems

Hand Feel: Soft

Certifications: OEKO-TEX®

COMPOSITION

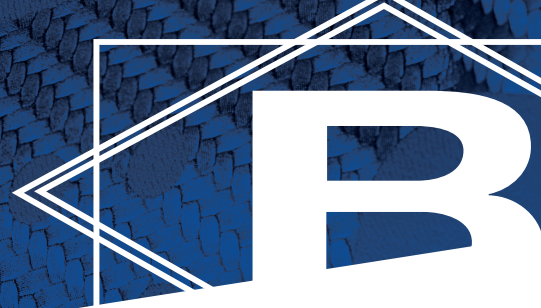
Ester Polyurethane

THERMAL & PHYSICAL PROPERTIES

STOCKED COLOR	Clear
STOCKED WIDTH	1524mm (60") – product can be slit to requested widths, no less than 4 mm (.16")
GAUGE	50 µm (.002"), 75 µm (.003"), 150 µm (.006")
ADHESIVE WEIGHT	31 g/m ² (per 25 µm)
RELEASE LINER	Silicone Coated Paper
SOFTENING POINT	83°C (181°F)
MELT FLOW INDEX	45 dg/min at 175°C / 2.16 kg
GLUE LINE TEMPERATURE¹	110°C to 140°C (230°F to 284°F)

¹ Glue Line Temperature relates to the temperature the adhesive must reach during bonding to achieve optimal bond strength.

PRODUCT DATA INFORMATION



DURABILITY TESTING

Modulus & Recovery:

GAUGE	MODULUS OF 25.4MM (1") WIDE SAMPLE		RECOVERY AFTER 100% ELONGATION AT A RATE OF 304MM (12") PER MINUTE
	@ 40% of original length	@ 100% of original length	
50 µm (.002")	0.8 lbf/in	1.4 lbf/in	96%

Wash/Dry: Excellent up to 60°C

RECOMMENDED BONDING CONDITIONS²

FLAT PRESS:

TEMPERATURE	120°C to 130°C
TIME	20 to 30 seconds
PRESSURE	40 to 60 psi (2.8 to 4.2 bar)

CONTINUOUS BONDING MACHINE:

TEMPERATURE	200°C to 250°C
PRESSURE	14.3 psi (1.0 bar)
SPEED	1.5 to 2.0 m/min

² Recommended bonding conditions will vary between machinery, fabrics and applications. Optimal bonding conditions should be established by Bemis and the customer for each application prior to production.